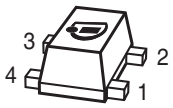
Low Noise Silicon Bipolar RF Transistor



- For low current applications
- Minimum noise figure NF_{min} = 1.25 dB at 1.8 GHz
  Outstanding G_{ms} = 22.5 dB at 1.8 GHz
- Transition frequency f_T = 25 GHz
- Pb-free (RoHS compliant) and halogen-free thin small flat package (1.4 x 0.8 x 0.59 mm) with visible leads
- Qualification report according to AEC-Q101 available

RoHS

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFP405F	ALs	1=B	2=E	3=C	4=E	-	-	TSFP-4

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}		V
T_A = 25 °C		4.5	
T_A = -55 °C		4.1	
Collector-emitter voltage	V_{CES}	15	
Collector-base voltage	V_{CBO}	15	
Emitter-base voltage	V_{EBO}	1.5	
Collector current	I_C	25	mA
Base current	I_B	3	
Total power dissipation[1)] $T_S \leq 112$ °C	P_{tot}	75	mW
Junction temperature	T_J	150	°C
Storage temperature	T_{Stg}	-55 ... 150	

[1] T_S is measured on the emitter lead at the soldering point to the pcb

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[1)]	R_{thJS}	500	K/W

Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 1 mA, I_B = 0	$V_{(BR)CEO}$	4	5	-	V
Collector-emitter cutoff current V_{CE} = 15 V, V_{BE} = 0	I_{CES}	-	-	10	µA
Collector-base cutoff current V_{CB} = 5 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 0.5 V, I_C = 0	I_{EBO}	-	-	1	µA
DC current gain I_C = 5 mA, V_{CE} = 4 V, pulse measured	h_{FE}	60	95	130	-

[1]For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)

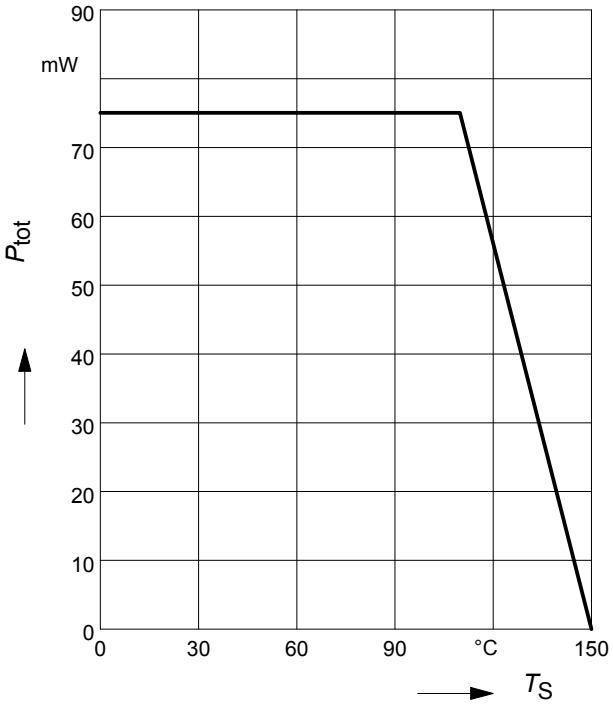
Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency I_C = 10 mA, V_{CE} = 3 V, f = 2 GHz	f_T	18	25	-	GHz
Collector-base capacitance V_{CB} = 2 V, f = 1 MHz, V_{BE} = 0 , emitter grounded	C_{cb}	-	0.05	0.1	pF
Collector emitter capacitance V_{CE} = 2 V, f = 1 MHz, V_{BE} = 0 , base grounded	C_{ce}	-	0.2	-	
Emitter-base capacitance V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded	C_{eb}	-	0.25	-	
Minimum noise figure I_C = 2 mA, V_{CE} = 2 V, f = 1.8 GHz, $Z_S = Z_{Sopt}$	NF_{min}	-	1.25	-	dB
Power gain, maximum stable[1)] I_C = 5 mA, V_{CE} = 2 V, $Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$, f = 1.8 GHz	G_{ms}	-	22.5	-	dB
Insertion power gain V_{CE} = 2 V, I_C = 5 mA, f = 1.8 GHz, $Z_S = Z_L$ = 50 Ω	$\lvert S_{21}\rvert^2$	-	18	-	
Third order intercept point at output[2)] V_{CE} = 2 V, I_C = 5 mA, f = 1.8 GHz, $Z_S = Z_L$ = 50 Ω	$IP3$	-	14	-	dBm
1dB compression point at output I_C = 5 mA, V_{CE} = 2 V, $Z_S = Z_L$ = 50 Ω, f = 1.8 GHz	P_{-1dB}	-	0	-	

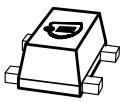
[1] $G_{ms} = |S_{21} / S_{12}|$

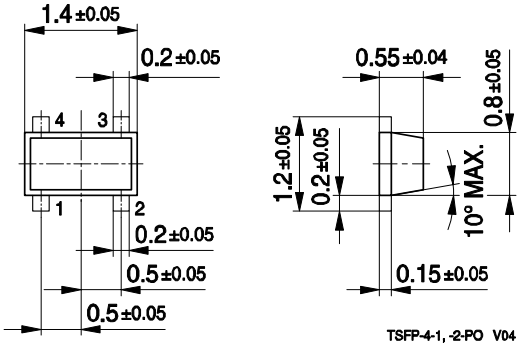
[2] IP3 value depends on termination of all intermodulation frequency components.
Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

Total power dissipation $P_{tot} = f(T_S)$

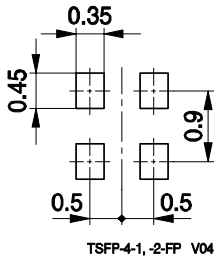


Package Outline

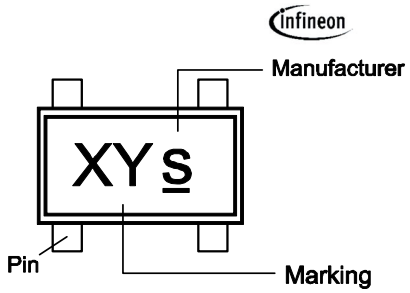




Foot Print

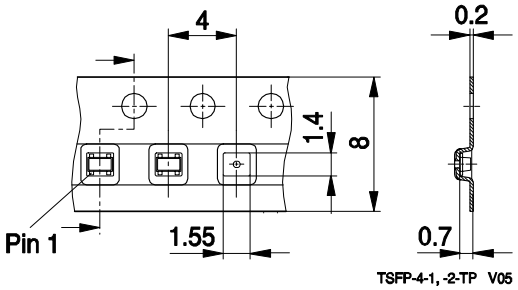


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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